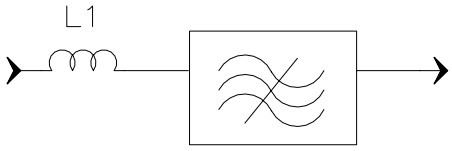
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	124.8	125	125.2
Insertion Loss	dB	-	24	26
1 dB Bandwidth	MHz	29.2	29.75	-
3 dB Bandwidth	MHz	30	30.78	-
50 dB Bandwidth	MHz	-	34	35
Passband Variation	dB	-	0.8	1.0
Absolute Delay	usec	-	1.29	-
Group Delay Variation(f0±14.5MHz)	nsec	-	25	-
Ultimate Rejection	dB	50	55	-
Material Temperature coefficient	KHz/°C	-10.25		
Ambient Temperature	°C	25		
Package Size	DIP2012 (20x12.5x4mm^3)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration

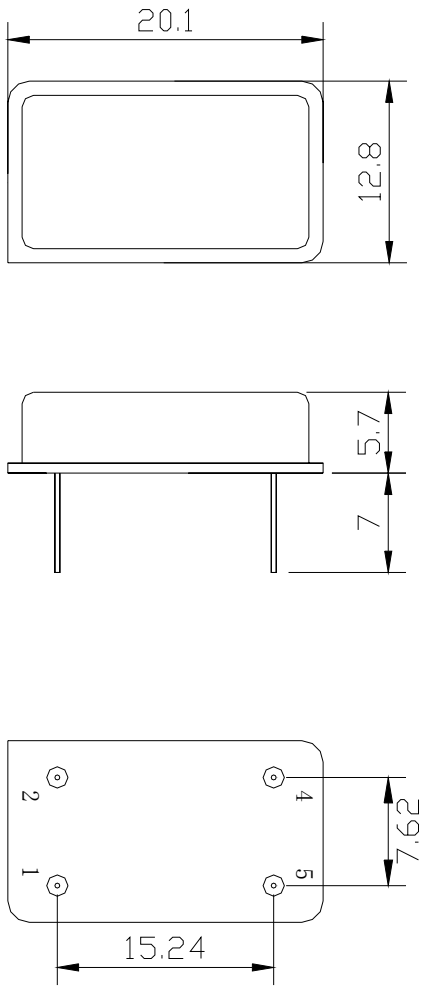


L1=82nH

Source/Load Impedance=50 ohm

Notes - Component values may change depending on board layout.

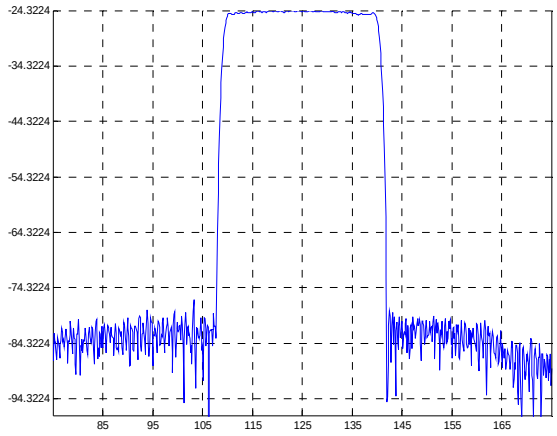
Package Dimension



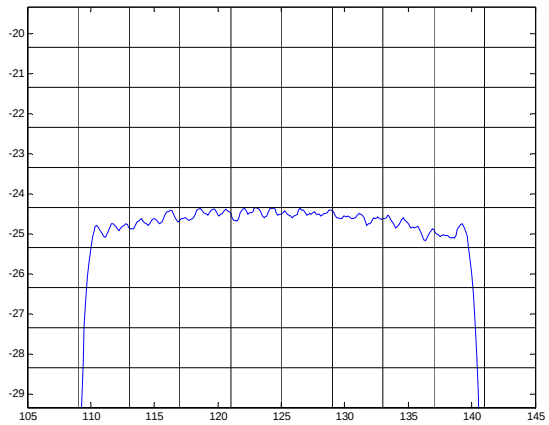
Input:1
Output:5

Typical Performance

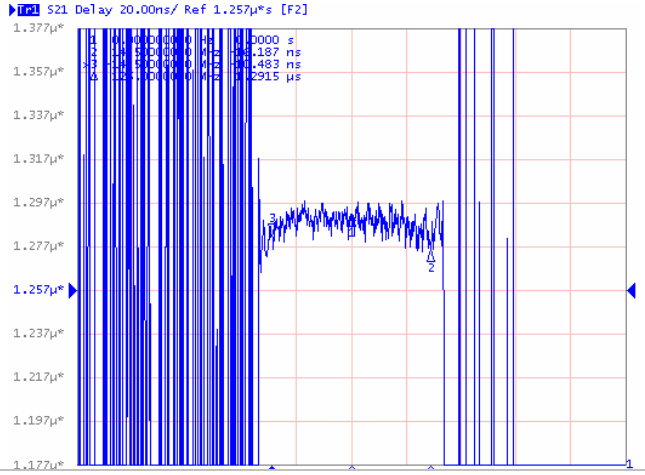
Frequency Respond



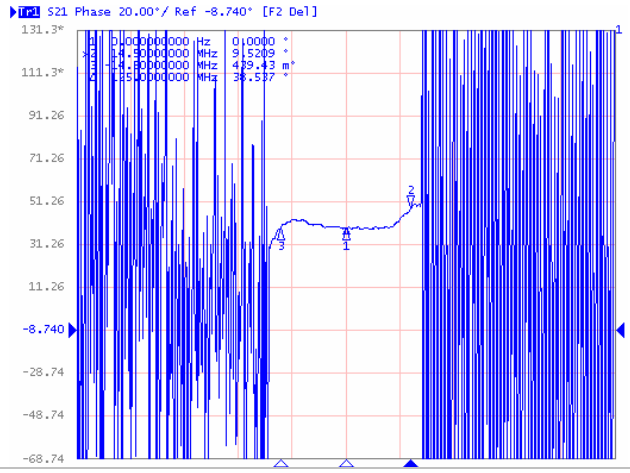
Passband Respond



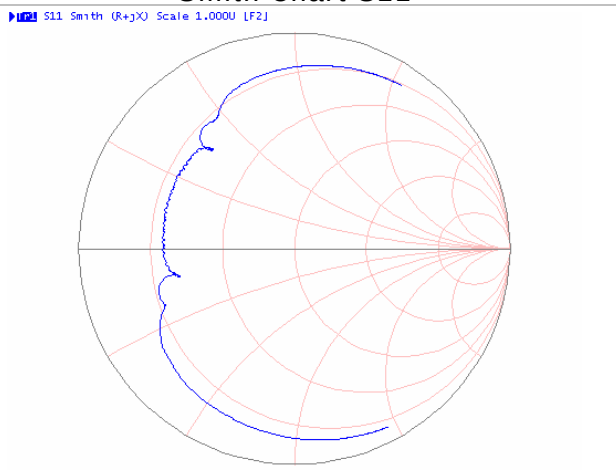
Group Delay Variation(f0±14.5Hz)



Phase Linearity(f0±14.5Hz)



Smith Chart S11



Smith Chart S22

